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**Nanomanufacturing – Large scale manufacturing for nanoelectronics**

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ELECTROTECHNICAL  
COMMISSION

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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# NANOMANUFACTURING – LARGE SCALE MANUFACTURING FOR NANOELECTRONICS

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The text of this standard is based on the following documents:

FDIS	Report on voting
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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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The IEC Technical Committee and IEEE Technical Committee have decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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<sup>1</sup> A list of IEEE participants can be found at the following URL: [http://standards.ieee.org/downloads/62659/62659-2015/62659-2015\\_wg-participants.pdf](http://standards.ieee.org/downloads/62659/62659-2015/62659-2015_wg-participants.pdf)

## INTRODUCTION

In order to fully benefit from the cost, performance, and flexibility of new electronics products manufactured on a large-scale, industries accustomed to the purchase, use, and engineering of continuum materials need to grow to embrace appropriate new practices at the nanoscale. The purpose of this International Standard is to enable the quick, low-risk adoption of nanomaterials into large-scale electronics manufacturing. In addition a best set of common practices for use by semiconductor fabricators will be delineated.

The description of nanomaterials to be incorporated into the electronics process can be described in terms of: composition (material), density, purity, size/dimensions, properties such as electrical characteristics (conductive, non-conductive, and semiconductive), associated media (delivery medium), fabrication, surface functionalization, particle size distribution, surface area, shape, and degree of aggregation and agglomeration, etc.

These standards for the characterization of nanomaterials also provide an opportunity to help ensure consistency in metrics and measurement methods when specifying or producing nanomaterials for electronics applications. This is important when multiple vendors or technology partners are involved.

## **NANOMANUFACTURING – LARGE SCALE MANUFACTURING FOR NANOELECTRONICS**

### **1 Scope**

This International Standard provides a framework for introducing nanoelectronics into large scale, high volume production in semiconductor manufacturing facilities through the incorporation of nanomaterials (e.g. carbon nanotubes, graphene, quantum dots, etc.). Since semiconductor manufacturing facilities need to incorporate practices that maintain high yields, there are very strict requirements for how manufacturing is performed. Nanomaterials represent a potential contaminant in semiconductor manufacturing facilities and need to be introduced in a structured and methodical way.

This International Standard provides steps employed to facilitate the introduction of nanomaterials into the semiconductor manufacturing facilities. This sequence is described below under the areas of raw materials acquisition, materials processing, design, IC fabrication, testing, and end-use. These activities represent the major stages of the supply chain in semiconductor manufacturing facilities.

### **2 Normative references**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

*None.*